

**SCHOTTKY BARRIER RECTIFIERS  
For PV Solar Cell Bypass Protection**

REVERSE VOLTAGE – 40 to 45 Volts  
FORWARD CURRENT – 20 Amperes

**FEATURES**

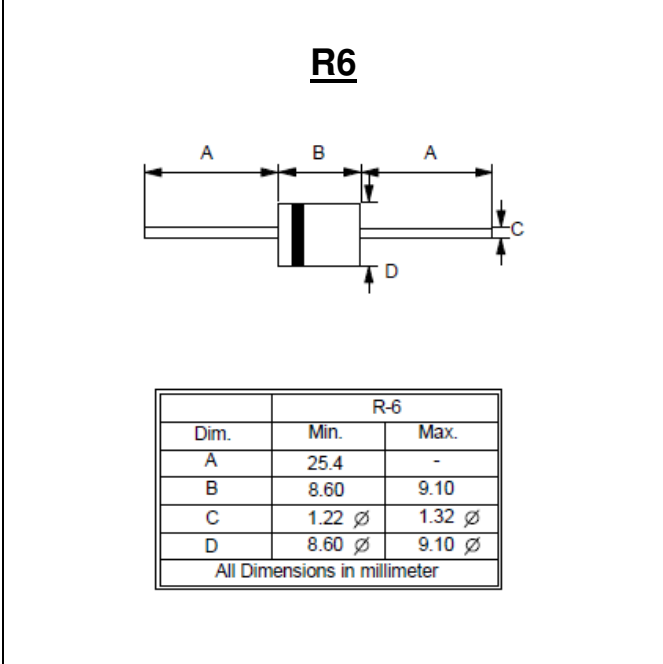
- Metal of silicon rectifier, majority carrier conduction
- Guard ring for transient protection
- Low power loss, high efficiency
- High surge&current capability, low VF
- IEC 61000-4-2 (ESD), >±30KV(air), >±15KV(contact)

**APPLICATION**

- For use in Solar Cell junction box as a bypass diode for protection, using DC forward current without reverse bias

**MECHANICAL DATA**

- Case: JEDEC R-6 molded plastic
- Polarity : Color band denotes cathode
- Weight : 0.07 ounces, 2.1grams
- Mounting position: Any
- Soldering condition : Temp 260°C±5 (Duration 10±1s)



**MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS**  
Ratings at 25°C ambient temperature unless otherwise specified.

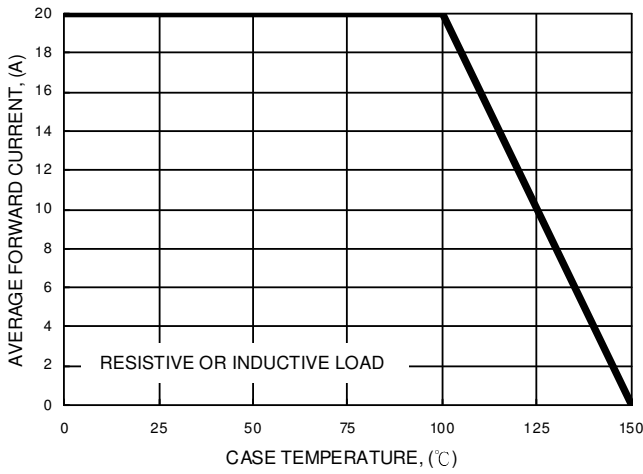
PARAMETER	SYMBOL	20SQ040	20SQ045	UNIT
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	40	45	V
Maximum DC Blocking Voltage	$V_{DC(AV)}$	40	45	V
Average Rectified Output Current @ $T_c=100^\circ C$	$I_F$	20		A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rated load	$I_{FSM}$	275		A
Maximum Forward Voltage at 20A DC Note (1) $T_j=25^\circ C$	$V_F$	0.55		V
Maximum DC Reverse Current at Rated DC Blocking Voltage $T_j=25^\circ C$ $T_j=100^\circ C$	$I_R$	1.0 100		mA
Typical thermal resistance Junction to Lead (Note 3)	$R_{\theta JL}$	2.0		°C/W
Typical thermal resistance Junction to Case (Note 3)	$R_{\theta JC}$	7.0		
Typical thermal resistance Junction to Ambient (Note 3)	$R_{\theta JA}$	40		
Typical Thermal Resistance (Note 2)	$C_J$	1300		pF
Operating junction temperature	$T_J$	150		°C
Junction temperature in DC forward current without reverse bias, $t \leq 1$ h	$T_J$ (Note 4)	$\leq 200$		°C
Storage temperature range	$T_{STG}$	-55 to +150		°C

Note :

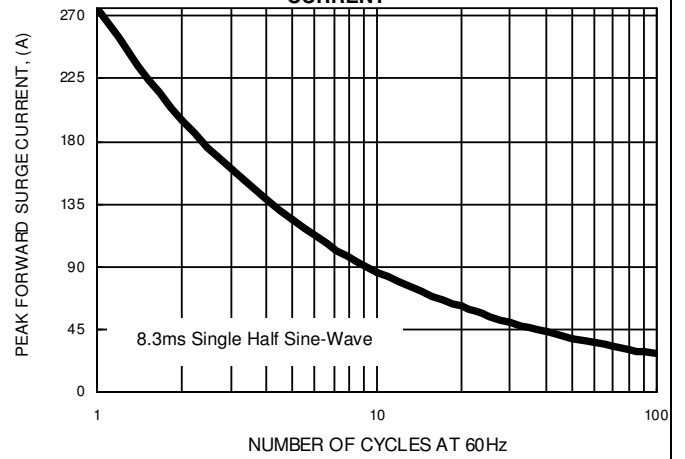
- (1) 300us Pulse Width, 2% Duty Cycle.
- (2) Measured at 1.0MHz and applied reverse voltage of 4.0  $V_{DC}$ .
- (3) Thermal Resistance test performed in accordance with JESD-51.
- (4) Meets the requirement of IEC 61215 ed. 2 bypass diode thermal test.

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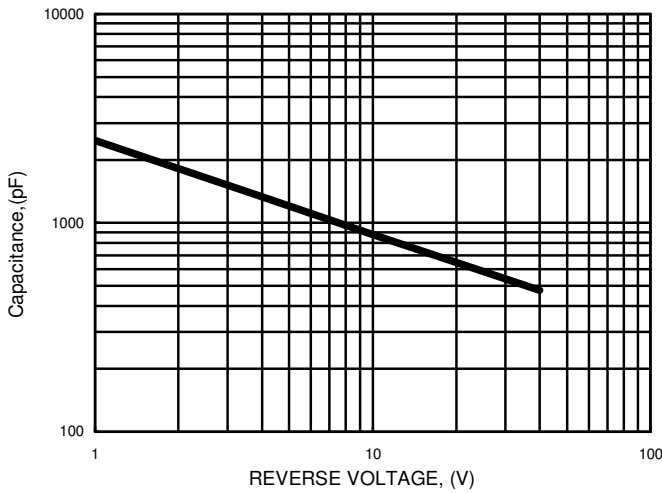
**FIG.1- FORWARD CURRENT DERATING CURVE**



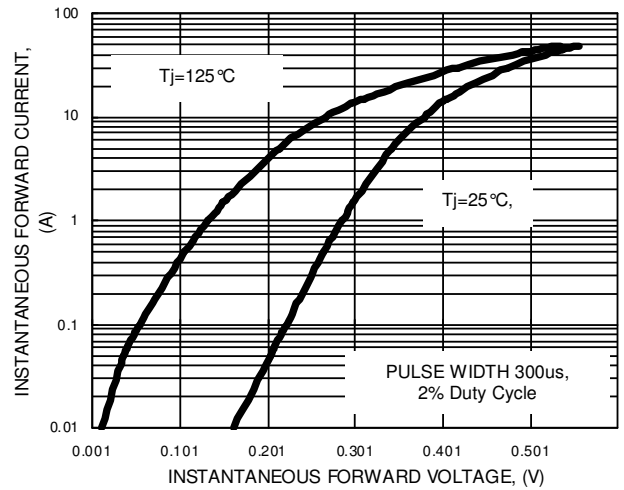
**FIG.2- MAXIMUM NON-REPETITIVE SURGE CURRENT**



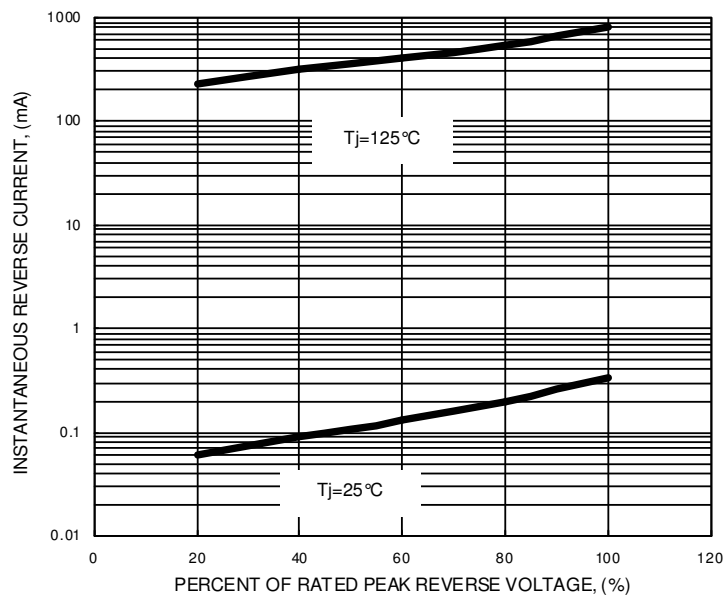
**FIG.3- TYPICAL JUNCTION CAPACITANCE**



**FIG.4- TYPICAL FORWARD CHARACTERISTICS**



**FIG.5- TYPICAL REVERSE CHARACTERISTICS**



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